MC3486 QUADRUPLE DIFFERENTIAL LINE RECEIVER WITH 3-STATE OUTPUTS

SLLS097C - JUNE 1980 - REVISED FEBRUARY 2002

Meets or Exceeds the Requirements of D, N, OR NS PACKAGE (TOP VIEW) ANSI Standards EIA/TIA-422-B and **EIA/TIA-423-B and ITU Recommendations** 1B 16 VCC V.10 and V.11 1A [15 AB 3-State, TTL-Compatible Outputs 14 🛮 4A 1Y **∏** 3 **Fast Transition Times** 1.2EN **∏** 4 13 T 4Y **Operates From Single 5-V Supply** 12 3,4EN 2Y 🛮 2A 11 3Y Designed to Be Interchangeable With 2B **∏** 7 10 3A Motorola™ MC3486 9 1 3B GND

description

The MC3486 is a monolithic quadruple differential line receiver designed to meet the specifications of ANSI Standards TIA/EIA-422-B and TIA/EIA-423-B and ITU Recommendations V.10 and V.11. The MC3486 offers four independent differential-input line receivers that have TTL-compatible outputs. The outputs utilize 3-state circuitry to provide a high-impedance state at any output when the appropriate output enable is at a low logic level.

The MC3486 is designed for optimum performance when used with the MC3487 quadruple differential line driver. It is supplied in a 16-pin package and operates from a single 5-V supply.

The MC3486 is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

	PACKAGED D	EVICES		
TA	PLASTIC SMALL OUTLINE (D, NS)	PLASTIC DIP (N)		
0°C to 70°C	MC3486D MC3486NS	MC3486N		

The D package is available taped and reeled. Add the suffix R to the device type (e.g., MC3486DR). The NS package is only available taped and reeled.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Motorola is a trademark of Motorola, Incorporated.

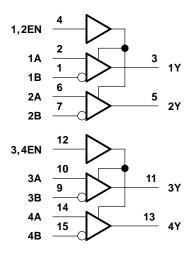


FUNCTION TABLE (each receiver)

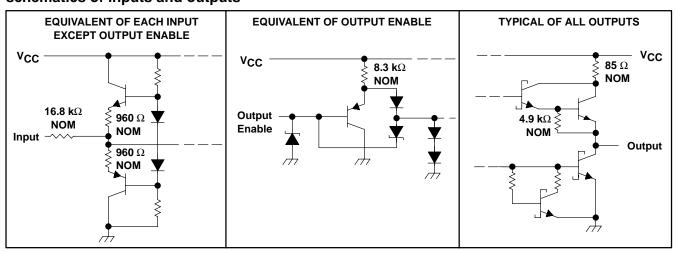
DIFFERENTIAL INPUTS A-B	ENABLE	OUTPUT Y
V _{ID} ≤ 0.2 V	Н	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	Н	?
$V_{ID} \le -0.2 V$	Н	L
Irrelevant	L	Z
Open	Н	?

H = high level, L = low level, Z = high impedance (off), ? = indeterminate

logic diagram (positive logic)



schematics of inputs and outputs





MC3486 QUADRUPLE DIFFERENTIAL LINE RECEIVER WITH 3-STATE OUTPUTS

SLLS097C - JUNE 1980 - REVISED FEBRUARY 2002

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	8 V
Input voltage, V _I (A or B inputs)	
Differential input voltage, V _{ID} (see Note 2)	
Enable input voltage	8 V
Low-level output current, IOL	
Package thermal impedance, θ _{JA} (see Note 3): D package	
N package	67°C/W
NS package	67°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential-input voltage, are with respect to network ground terminal.
 - 2. Differential-input voltage is measured at the noninverting input with respect to the corresponding inverting input.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.75	5	5.25	V
VIC	Common-mode input voltage			±7	V
VID	Differential input voltage			±6	V
VIH	High-level enable input voltage	2			V
VIL	Low-level enable input voltage			0.8	V
TA	Operating free-air temperature	0		70	°C

MC3486 QUADRUPLE DIFFERENTIAL LINE RECEIVER WITH 3-STATE OUTPUTS

SLLS097C - JUNE 1980 - REVISED FEBRUARY 2002

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITION	s	MIN	MAX	UNIT
V _{IT+}	Differential input high-threshold voltage	$V_0 = 2.7 \text{ V}, \qquad I_0 = -0.4 \text{ mA}$			0.2	V
V_{IT-}	Differential input low-threshold voltage	$V_{O} = 0.5 \text{ V}, \qquad I_{O} = -8 \text{ mA}$		-0.2†		V
V_{IK}	Enable-input clamp voltage	$I_{\parallel} = -10 \text{ mA}$			-1.5	V
Vон	High-level output voltage	V_{ID} = 0.4 V, I_{O} = -0.4 mA, See Note 4 and Figure 1		2.7		٧
VOL	Low-level output voltage	$V_{\text{ID}} = -0.4 \text{ V}, \qquad I_{\text{O}} = 8 \text{ mA},$ See Note 4 and Figure 1			0.5	٧
1	High-impedance-state output current	$V_{IL} = 0.8 \text{ V}, \qquad V_{ID} = -3 \text{ V},$	V _O = 2.7 V		40	
loz	nigh-impedance-state output current	$V_{IL} = 0.8 \text{ V}, \qquad V_{ID} = 3 \text{ V},$	$V_0 = 0.5 \text{ V}$		-40	μΑ
			$V_{I} = -10 \text{ V}$		-3.25	
	Differential-input bias current	V _{CC} = 0 V or 5.25 V,	$V_I = -3 V$		-1.5	m A
IВ	Differential-input bias current	Other inputs at 0 V	V _I = 3 V	1.5		mA
			V _I = 10 V		3.25	
1	High-level enable input current	V _I = 5.25 V		100		
lιΗ	nigir-ievei enable in p ut current	V _I = 2.7 V		20	μΑ	
IլL	Low-level enable input current	V _I = -0.5 V			-100	μΑ
los	Short-circuit output current	$V_{ID} = 3 V, V_{O} = 0,$	See Note 5	-15	-100	mA
ICC	Supply current	V _{IL} = 0	•		85	mA

[†] The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet for threshold voltages only.

NOTES: 4. Refer to ANSI Standards TIA/EIA-422-B and TIA/EIA-423-B for exact conditions.

5. Only one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPHL	Propagation delay time, high- to low-level output	See Figure 2		28	35	ns
tPLH	Propagation delay time, low- to high-level output	See Figure 2		27	30	ns
^t PZH	Output enable time to high level			13	30	ns
tPZL	Output enable time to low level	See Figure 3		20	30	ns
tPHZ	Output disable time from high level	See Figure 3		26	35	ns
^t PLZ	Output disable time from low level			27	35	ns



PARAMETER MEASUREMENT INFORMATION

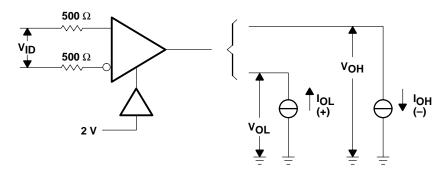
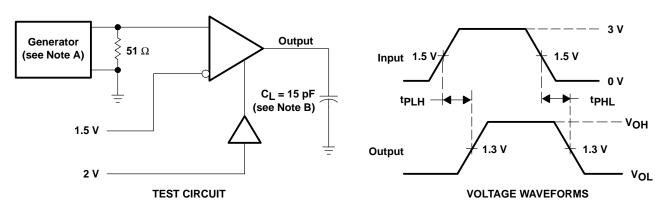


Figure 1. V_{OH}, V_{OL}

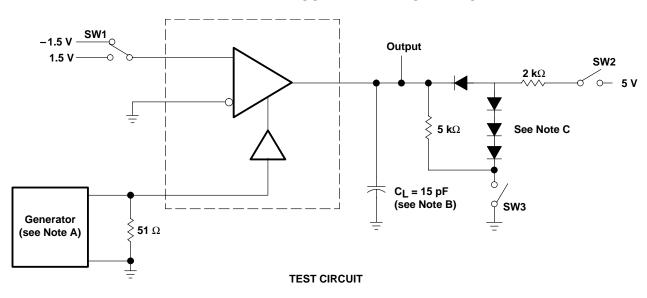


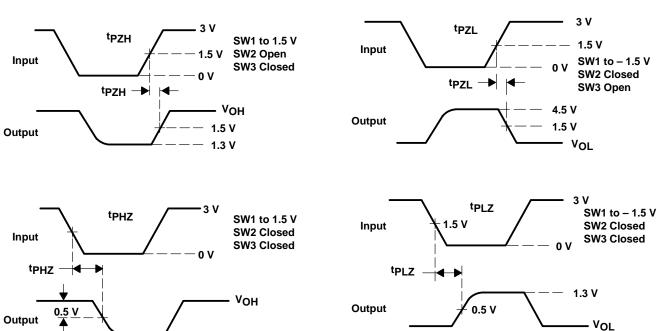
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_{f} \leq$ 6 ns, $t_{f} \leq$ 6 ns.

B. C_L includes probe and stray capacitance.

Figure 2. Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION





NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_f \leq$ 6 ns, $t_f \leq$ 6 ns.

B. CL includes probe and stray capacitance.

1.3 V

C. All diodes are 1N916 or equivalent.

Figure 3. Test Circuit and Voltage Waveforms



www.ti.com 14-Aug-2021

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
MC3486D	ACTIVE	SOIC	D	16	40	RoHS & Green	(6) NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples
MC3486DE4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples
MC3486DG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples
MC3486DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples
MC3486DRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples
MC3486N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	MC3486N	Samples
MC3486NE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	MC3486N	Samples
MC3486NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

www.ti.com 14-Aug-2021

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

	Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	MC3486DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
L	MC3486NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MC3486DR	SOIC	D	16	2500	340.5	336.1	32.0
MC3486NSR	SO	NS	16	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
MC3486D	D	SOIC	16	40	507	8	3940	4.32
MC3486DE4	D	SOIC	16	40	507	8	3940	4.32
MC3486DG4	D	SOIC	16	40	507	8	3940	4.32
MC3486N	N	PDIP	16	25	506	13.97	11230	4.32
MC3486N	N	PDIP	16	25	506	13.97	11230	4.32
MC3486NE4	N	PDIP	16	25	506	13.97	11230	4.32
MC3486NE4	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated